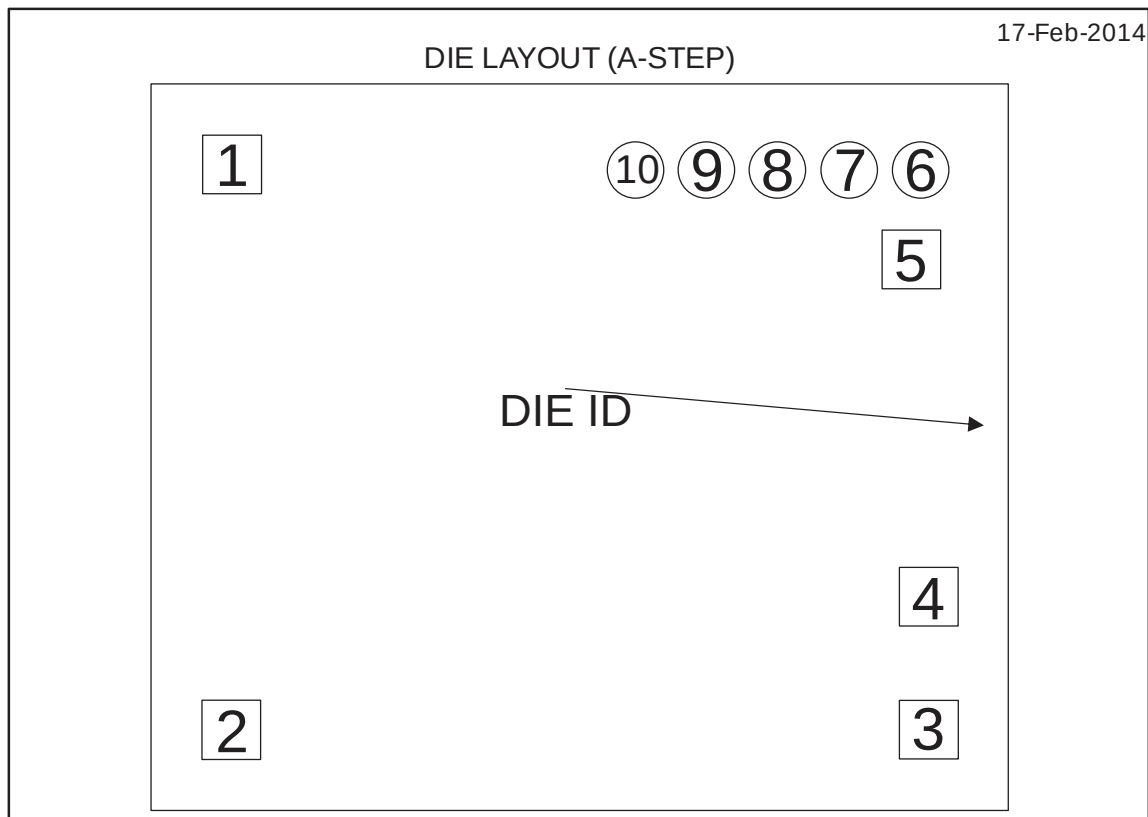


LP2985I30/DWA
MICROPOWER 150 MA LOW-NOISE ULTRA LOW-DROPOUT REGULATOR



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LP2985A	Bond Pad Opening Size (min)	800.00 μm x 80.00 μm
Die Step	A	Bond Pad Metalization	Al CU 0.5%
Physical Attributes		Passivation	PECVDOX NITRIDE
Wafer Diameter	203.2 mm	Back Side Metal	BAREBACK
Die Size (DRAWN)	1168.4 μm x 990.6 μm 46.0 mils x 39.0 mils	Bad Side Connection	GND
Thickness	No Backgrind		
Min Pitch	180.50 μm		
Note: All values are rounded to the nearest micron. Products are processed to commercial wafer fab and visual criteria. Products are offered with a conditional performance verified to the standard product specifications. Full datasheet electrical performance is not ensured.			
Special Assembly Requirements:			

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Die Bond Pad Coordinate Locations(A-Step)						
(Reference to die center, coordinate in μm) NC = No Connection, N.U. = Not Used						
Signal name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X	Y	
VIN	1	-474.00	385.50	80.00	x	80.00
VOUT	2	-475.00	-386.50	80.00	x	80.00
BYPASS	3	474.00	-385.50	80.00	x	80.00
GND	4	474.00	-205.00	80.00	x	80.00
ON/OFF	5	450.00	256.00	80.00	x	80.00
NC	6	463.00	376.50	76.00	x	75.95
NC	7	366.50	376.50	76.00	x	75.95
NC	8	269.50	376.50	76.00	x	75.95
NC	9	172.50	376.50	76.00	x	75.95
NC	10	75.50	376.50	76.00	x	75.95

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